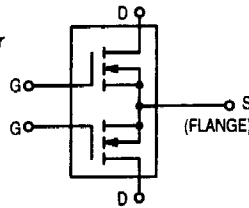


The RF MOSFET Line
RF Power
Field-Effect Transistors
N-Channel Enhancement-Mode

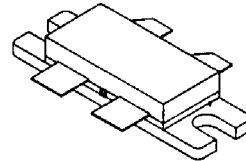
Designed for broadband commercial and military applications using push pull circuits at frequencies to 500 MHz. The high power, high gain and broadband performance of these devices makes possible solid state transmitters for FM broadcast or TV channel frequency bands.

- **Guaranteed Performance**
MRF175GV @ 28 V, 225 MHz ("V" Suffix)
Output Power — 200 Watts
Power Gain — 14 dB Typ
Efficiency — 65% Typ
MRF175GU @ 28 V, 400 MHz ("U" Suffix)
Output Power — 150 Watts
Power Gain — 12 dB Typ
Efficiency — 55% Typ
- 100% Ruggedness Tested At Rated Output Power
- Low Thermal Resistance
- Low C_{rss} — 20 pF Typ @ $V_{DS} = 28$ V



MRF175GU
MRF175GV

200/150 WATTS, 28 V, 500 MHz
N-CHANNEL MOS
BROADBAND
RF POWER FETs



CASE 375-04, STYLE 2

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	65	Vdc
Drain-Gate Voltage ($R_{GS} = 1.0$ M Ω)	V_{DGR}	65	Vdc
Gate-Source Voltage	V_{GS}	± 40	Vdc
Drain Current — Continuous	I_D	26	Adc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	400 2.27	Watts W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$
Operating Junction Temperature	T_J	200	$^\circ\text{C}$

THERMAL CHARACTERISTICS

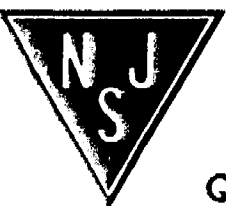
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.44	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS (1)

Drain-Source Breakdown Voltage ($V_{GS} = 0$, $I_D = 50$ mA)	$V_{(BR)DSS}$	65	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 28$ V, $V_{GS} = 0$)	I_{DSS}	—	—	2.5	mAdc
Gate-Source Leakage Current ($V_{GS} = 20$ V, $V_{DS} = 0$)	I_{GSS}	—	—	1.0	μAdc



NJ Semi-Conductors reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by NJ Semi-Conductors is believed to be both accurate and reliable at the time of going to press. However, NJ Semi-Conductors assumes no responsibility for any errors or omissions discovered in its use. NJ Semi-Conductors encourages customers to verify that datasheets are current before placing orders.

ELECTRICAL CHARACTERISTICS — continued ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
ON CHARACTERISTICS (1)					
Gate Threshold Voltage ($V_{DS} = 10\text{ V}, I_D = 100\text{ mA}$)	$V_{GS(th)}$	1.0	3.0	6.0	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ V}, I_D = 5.0\text{ A}$)	$V_{DS(on)}$	0.1	0.9	1.5	Vdc
Forward Transconductance ($V_{DS} = 10\text{ V}, I_D = 2.5\text{ A}$)	g_{fs}	2.0	3.0	—	mhos

DYNAMIC CHARACTERISTICS (1)

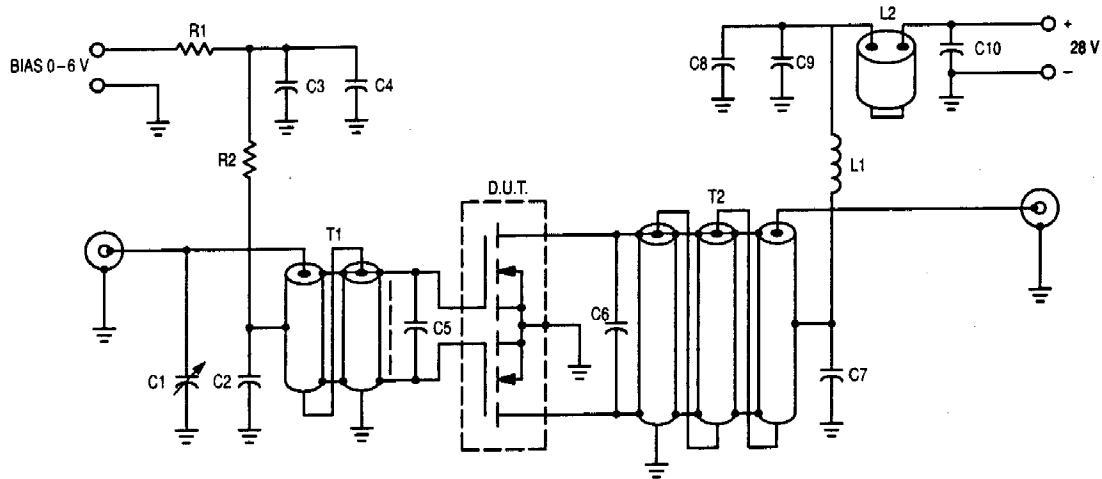
Input Capacitance ($V_{DS} = 28\text{ V}, V_{GS} = 0, f = 1.0\text{ MHz}$)	C_{iss}	—	180	—	pF
Output Capacitance ($V_{DS} = 28\text{ V}, V_{GS} = 0, f = 1.0\text{ MHz}$)	C_{oss}	—	200	—	pF
Reverse Transfer Capacitance ($V_{DS} = 28\text{ V}, V_{GS} = 0, f = 1.0\text{ MHz}$)	C_{rss}	—	20	—	pF

FUNCTIONAL CHARACTERISTICS — MRF175GV (2) (Figure 1)

Common Source Power Gain ($V_{DD} = 28\text{ Vdc}, P_{out} = 200\text{ W}, f = 225\text{ MHz}, I_{DQ} = 2.0 \times 100\text{ mA}$)	G_{ps}	12	14	—	dB
Drain Efficiency ($V_{DD} = 28\text{ Vdc}, P_{out} = 200\text{ W}, f = 225\text{ MHz}, I_{DQ} = 2.0 \times 100\text{ mA}$)	η	55	65	—	%
Electrical Ruggedness ($V_{DD} = 28\text{ Vdc}, P_{out} = 200\text{ W}, f = 225\text{ MHz}, I_{DQ} = 2.0 \times 100\text{ mA},$ VSWR 10:1 at all Phase Angles)	ψ	No Degradation in Output Power			

NOTES:

1. Each side of device measured separately.
2. Measured in push-pull configuration.



- C1 — Arco 404, 8.0–60 pF
- C2, C3, C7, C8 — 1000 pF Chip
- C4, C9 — 0.1 μF Chip
- C5 — 180 pF Chip
- C6 — 100 pF and 130 pF Chips in Parallel
- C10 — 0.47 μF Chip, Kemet 1215 or Equivalent
- L1 — 10 Turns AWG #16 Enamel Wire, Close Wound, 1/4" I.D.
- L2 — Ferrite Beads of Suitable Material for 1.5–2.0 μH Total Inductance

Board material — .062" fiberglass (G10),
Two sided, 1 oz. copper, $\epsilon_r \approx 5$
Unless otherwise noted, all chip capacitors
are ATC Type 100 or Equivalent.

- R1 — 100 Ohms, 1/2 W
- R2 — 1.0 k Ohm, 1/2 W
- T1 — 4:1 Impedance Ratio RF Transformer.
Can Be Made of 25 Ohm Semirigid Coax,
47–52 Mils O.D.
- T2 — 1:9 Impedance Ratio RF Transformer.
Can Be Made of 15–18 Ohms Semirigid
Coax, 62–90 Mils O.D.

NOTE: For stability, the input transformer T1 should be loaded with ferrite toroids or beads to increase the common mode inductance. For operation below 100 MHz. The same is required for the output transformer.

Figure 1. 225 MHz Test Circuit

